



Track Triggers for HL-LHC

Alberto Annovi
On behalf of ATLAS, CMS and LHCb

Challenges for HL-LHC

+ High-Luminosity LHC

- + Goal $5E34 \text{ Hz/cm}^2$ (plan for $7E34$)
- + $300 \text{ fb}^{-1}/\text{anno} \rightarrow 3000 \text{ fb}^{-1}$ total

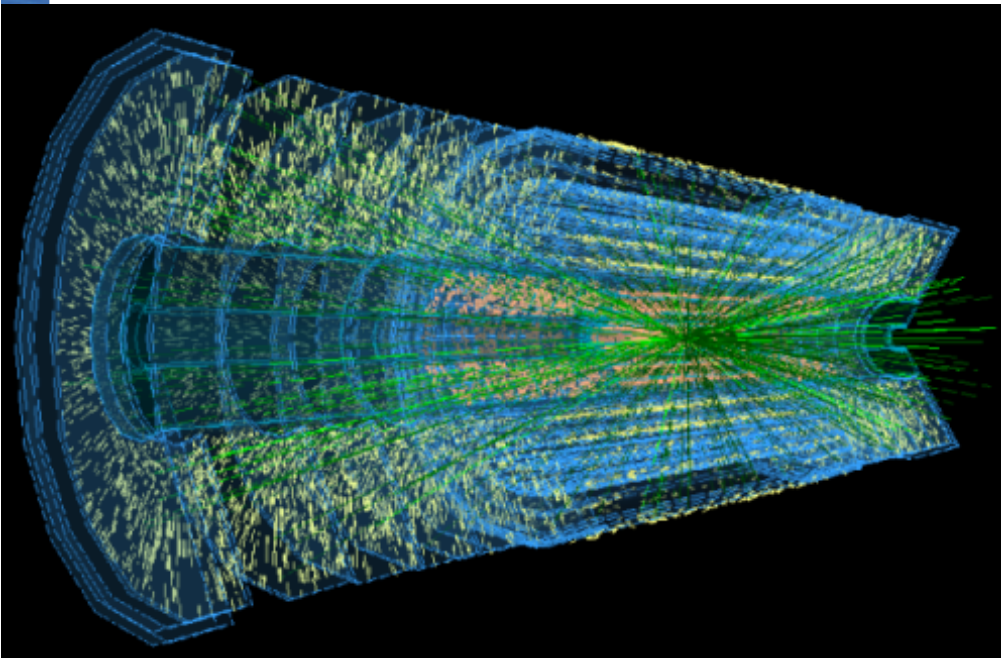
+ Higher occupancy

- + Pileup 140 (max 200)
- + Tracking more important!

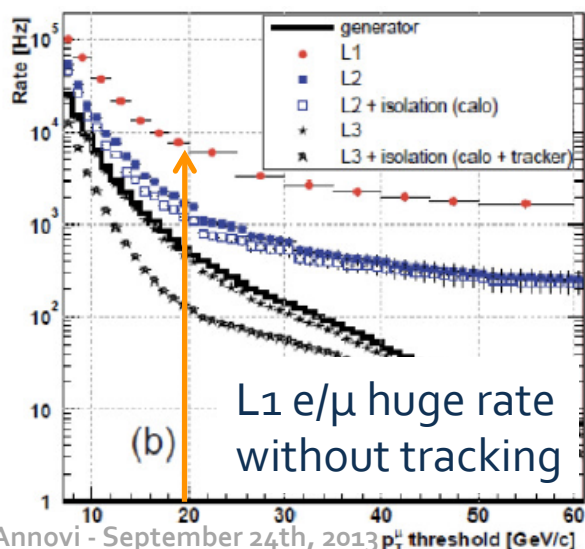
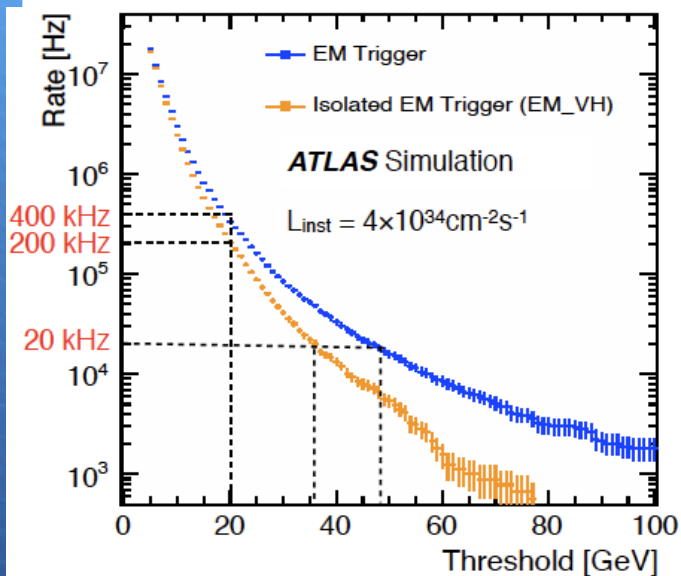
+ Increase trigger bandwidth

+ Move part of High Level Trigger (HLT) to L1

- + Including tracking
- + Low latency tracking $O(10\mu\text{s})$



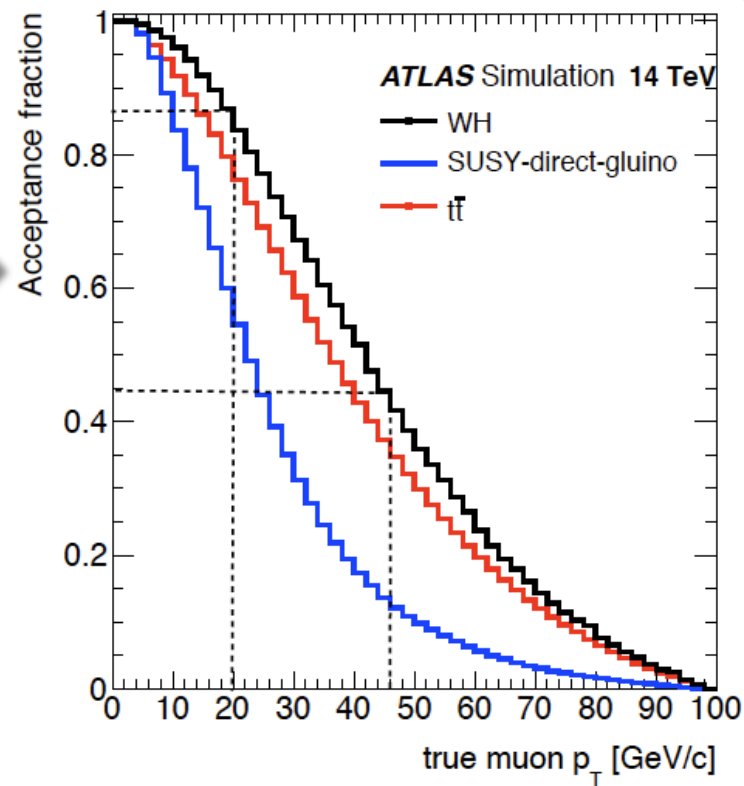
L1 Track for EWK pT leptons



ATLAS and CMS L1 Track:
 Need tracks at L1 in order to maintain
 $O(20 \text{ GeV})$ single mu/e p_T threshold



CMS 7TeV
 $10 E34 \text{Hz/cm}^2$



Strong interest for Track Triggers

+ ATLAS L2 (FTK)

- + Full tracking at 100kHz, $p_T > 1\text{GeV}$, ~offline-quality
- + Start data taking in 2015, upgrade during LS3

+ LHCb Track Processor

- + Recent studies on a "neural" track processor for LHC Phase-I
- + 40MHz, latency $\sim 1\mu\text{s}$. R&D for LHCb LS2

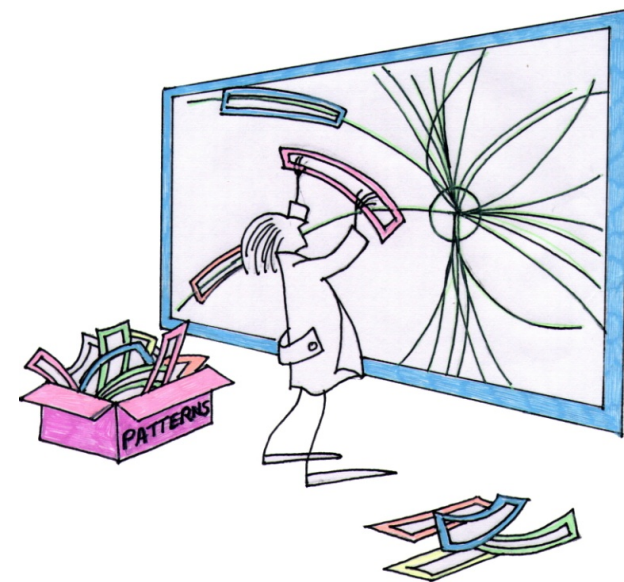
+ ATLAS L1 (L1Track) installation LS3

- + Regional tracking at 0.5-1MHz, seeded by L-zero
- + 20 μs latency, higher p_T threshold 5-10 GeV

+ CMS L1Track installation LS3

- + Self-seeded full tracking at 40MHz
- + Requires filtering of low p_T clusters ($p_T \sim < 2\text{GeV}$)
- + Latency 5 μs

+ 3 projects with same time scale (LS3) \rightarrow shared R&D



Strong interest for Track Triggers

+ LHCb Track Processor

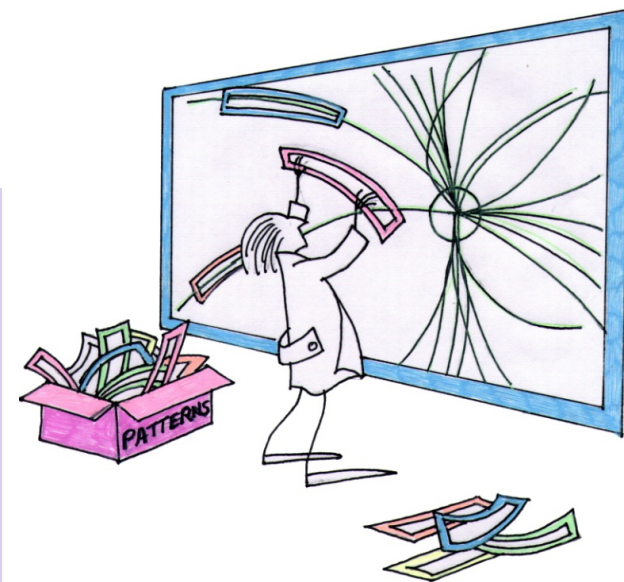
- + Recent studies on a "neural" track processor for LHC Phase-I
- + 40MHz, latency ~1 μ s, R&D for LHCb LS2

- AM finds track candidates with enough Si hits
- **FTK a total of $O(10^9)$ patterns (8k AM chips)**
- Patterns simultaneously see the silicon hits leaving the detector at full speed.
- **Pattern recognition is complete as soon as all data is received! \rightarrow very good fit with L1**
- Based on the Associative Memory initially developed for CDF.

L. Ristori, M. Dell'Orso NIM A **278**, 436 (1989)

- + Latency 10 μ s

+ 3 projects with same time scale \rightarrow shared R&D



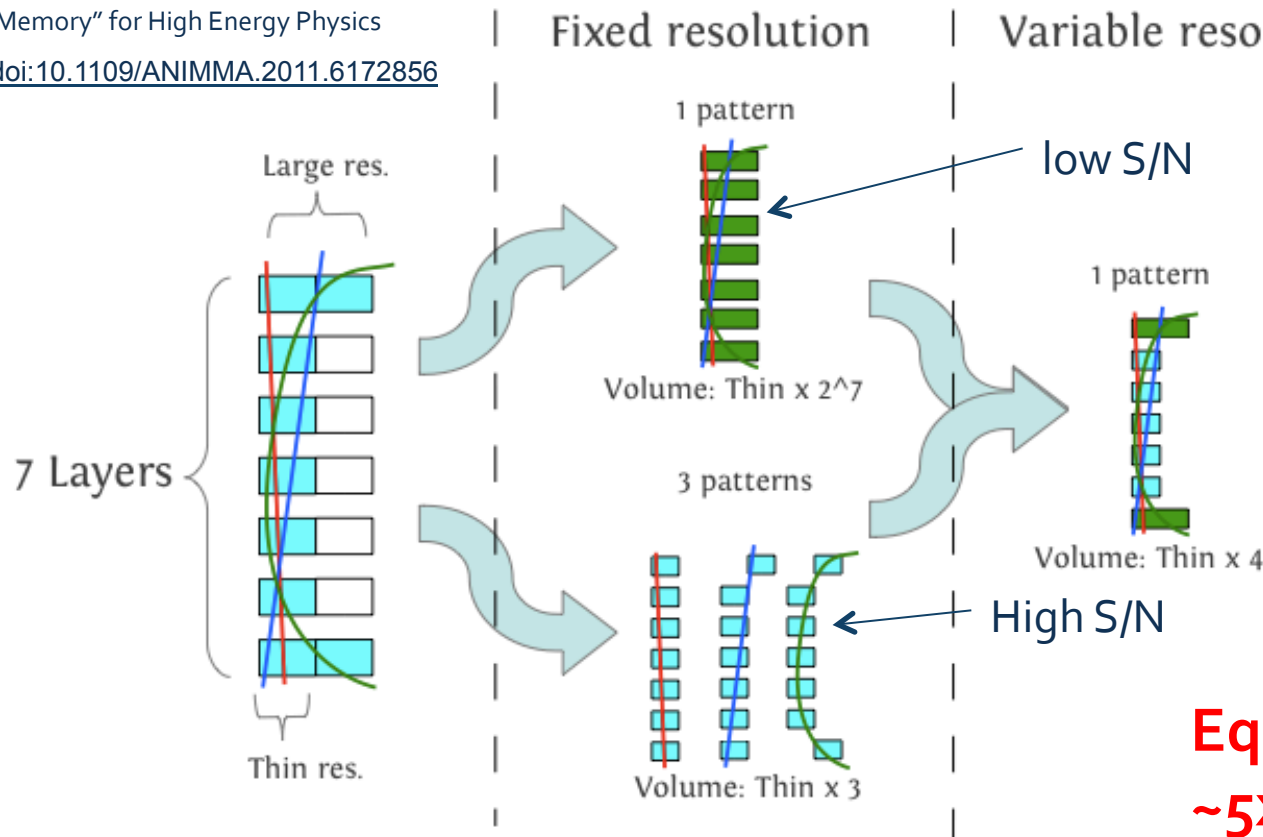
AMCHIP04: VARIABLE RESOLUTION

A new "Variable Resolution Associative Memory" for High Energy Physics

doi:10.1109/ANIMMA.2011.6172856



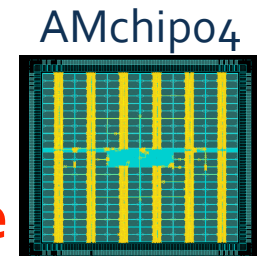
INFN Frascati



Good rejection and occupy only one pattern location.

Per-pattern choice of optimal resolution.

**Equivalent to
~5x patterns
→ 1/5 HW size**

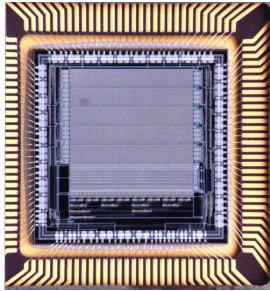


Implements the "don't care" feature: inspired by the Ternary CAMs

- Increases the width of a pattern only when needed (fully programmable)
- Wider patterns can be used in high occupancy regions, smaller patterns in low coverage regions (where the number of trajectories is low, thus reducing the fakes)
- The choice of wider or narrower width patterns is made layer by layer with simulation

AM technological evolution

SVT
AM chip



- (90's) **Full custom VLSI chip** - $0.7\mu\text{m}$ (INFN-Pisa)
 - **128 patterns, 6x12bit words each, 30MHz**
- F. Morsani et al., IEEE Trans. on Nucl. Sci., vol. 39 (1992)

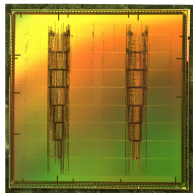


Alternative **FPGA** implementation of SVT AM chip

P. Giannetti et al., Nucl. Instr. and Meth., vol. A413/2-3, (1998)

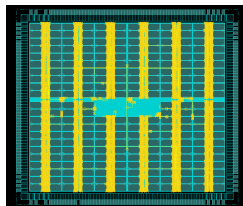
G Magazzù, 1st std cell project presented @ LHCC (1999)

SVT upgrade



Standard Cell $0.18\mu\text{m}$ \rightarrow 5000 pattern/AM chip
SVT upgrade total: 6M pattern, 40MHz
A. Annovi, L. Sartori et al., **IEEE TNS**, Vol 53, Issue 4, 2006

FTK R&D



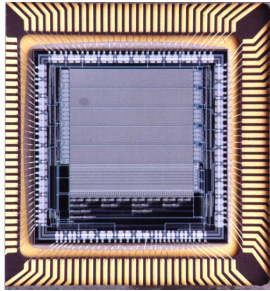
AMchip04 –65nm technology, std cell & full custom, 100MHz
Power/pattern/MHz ~30 times less. Pattern density x12.

First variable resolution implementation!

F. Alberti et al 2013 *JINST* 8 C01040, doi:[10.1088/1748-0221/8/01/C01040](https://doi.org/10.1088/1748-0221/8/01/C01040)

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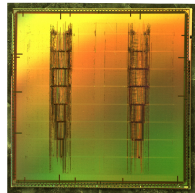
P. Giann
G Maga

FTK R&D in progress:

AMchip05 prototype: switch to serialized IO (11*2Gpbs)
submitted march 2014

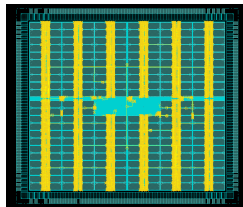
AMchip06 FTK final: increase area goal 128k patterns/chip
submission later in 2014

SVT upgrade



SVT upgrade total chip pattern density
A. Annovi, L. Sartori et al., **IEEE TNS**, Vol 53, Issue 4, 2006

FTK R&D



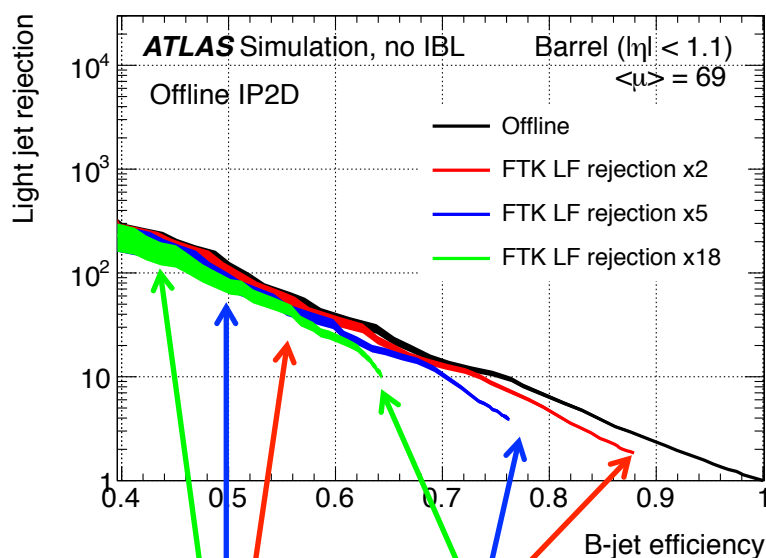
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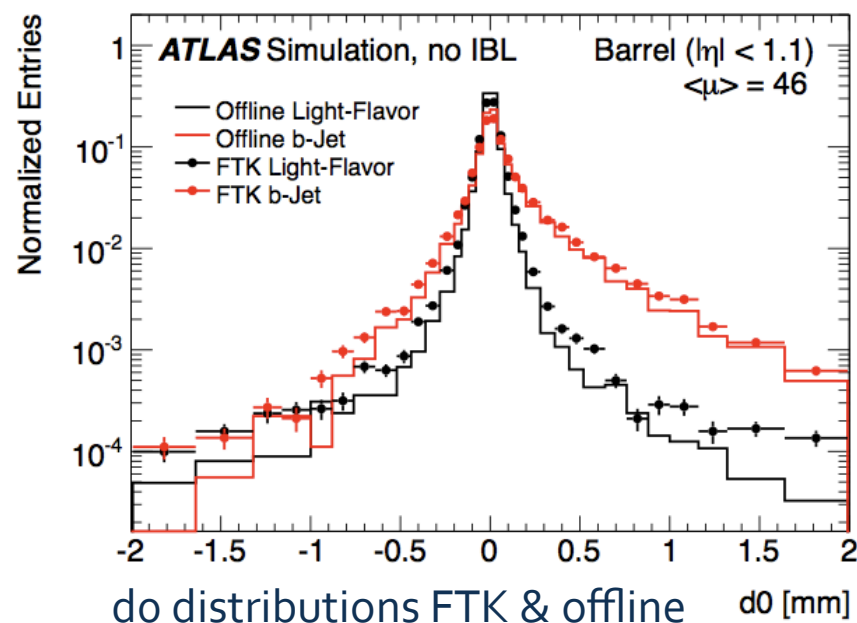
FTK example performance

Offline b-tagging (IP2D) applied to FTK (IP2D) selected samples.
Performance improvements in progress (adding IBL, better fit)



3 FTK working points at HLT

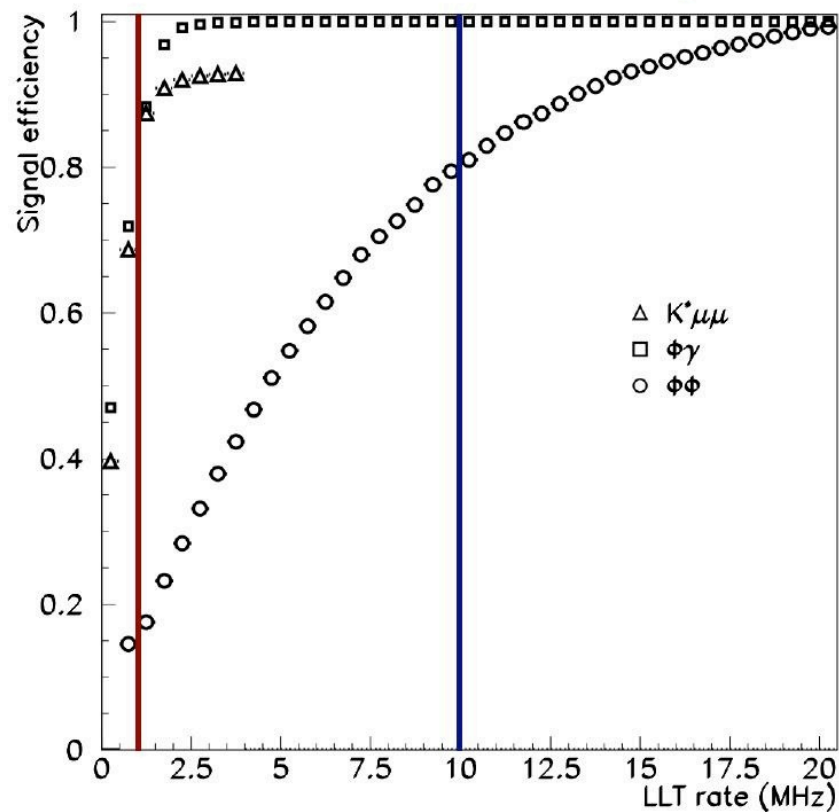
Colored curves show offline performance on FTK selected samples



do distributions FTK & offline

Offline performance no trigger

LHCb track trigger motivations

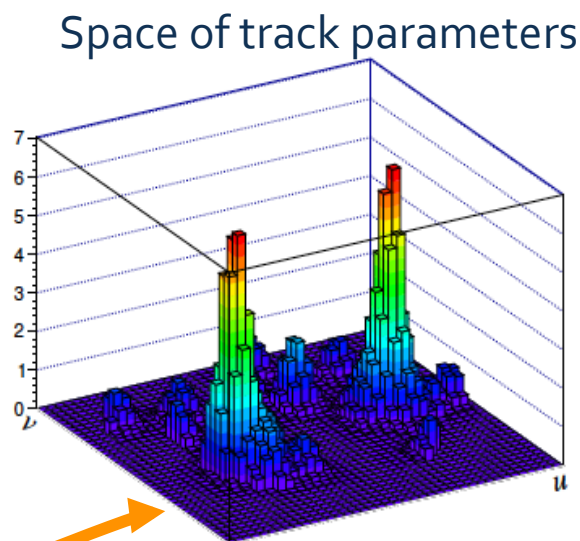
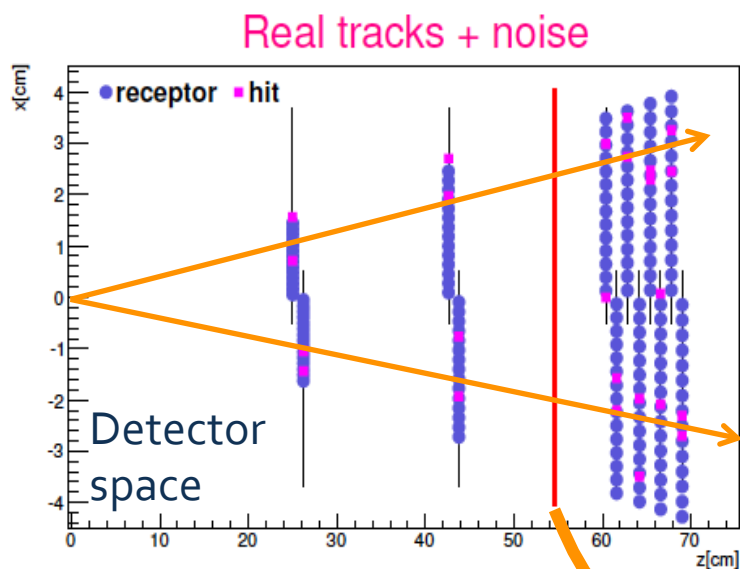


- + Good efficiency for hadronic decays required track trigger at high-rate
- + Plan is to collect data at full 30MHz and perform tracking

Neural processor: Tracks appear as clusters

Motivations: Tracking is essential for LHCb

G. Punzi @ INSTR14: <http://cern.ch/go/C6QS>



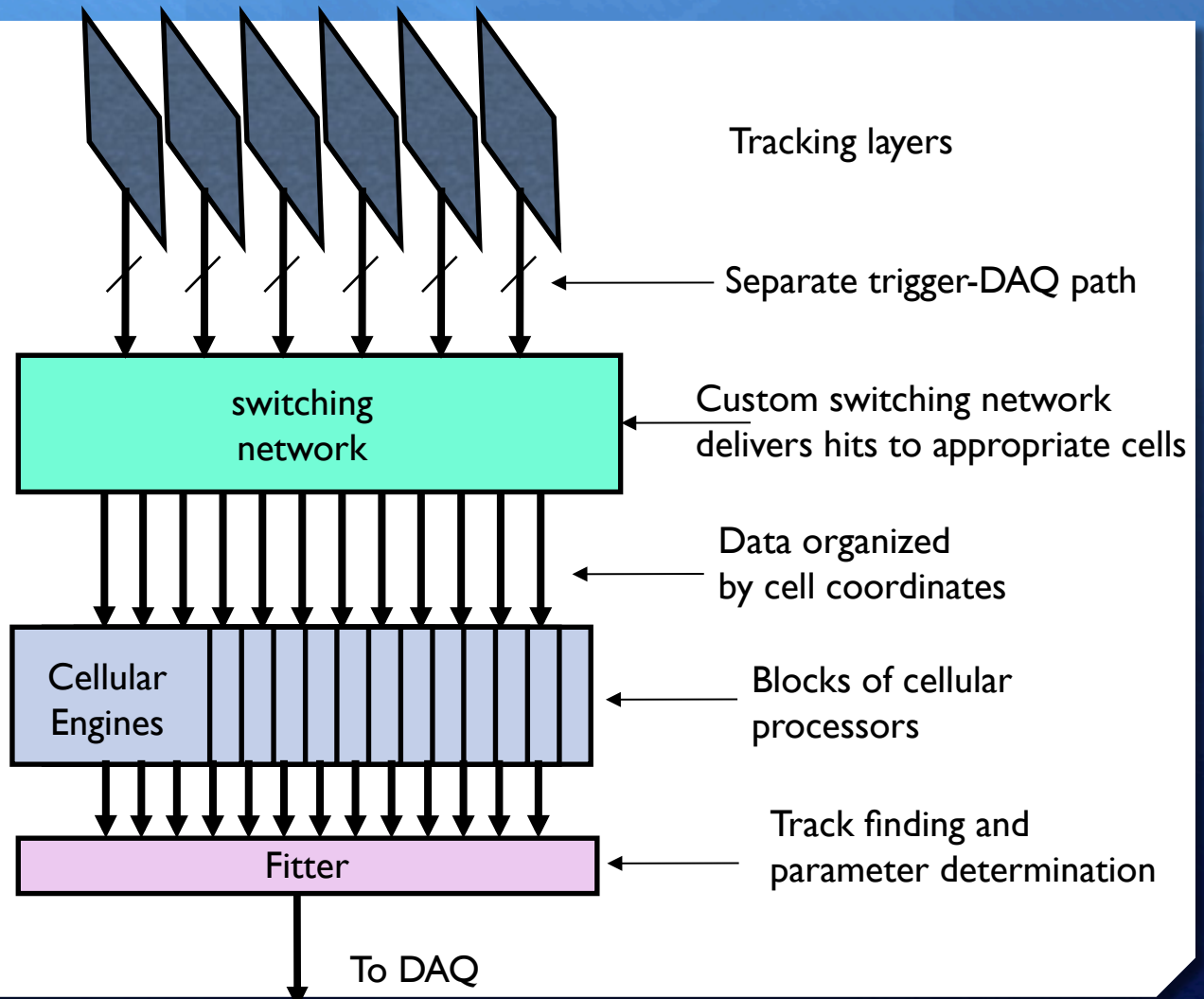
Track parameters estimated by cluster center interpolation

$$R_i = \sum_k e^{-s_{ir,k}^2/2\sigma^2}$$

$$s_{ir,k}^2 = (x_i - x_r)_k^2 + (y_i - y_r)_k^2$$

Distance of hit to nearby receptors

System Architecture



Stratix V FPGAs: Built for Bandwidth

Home > Devices > FPGAs > Stratix V (E, GX, GS, GT)

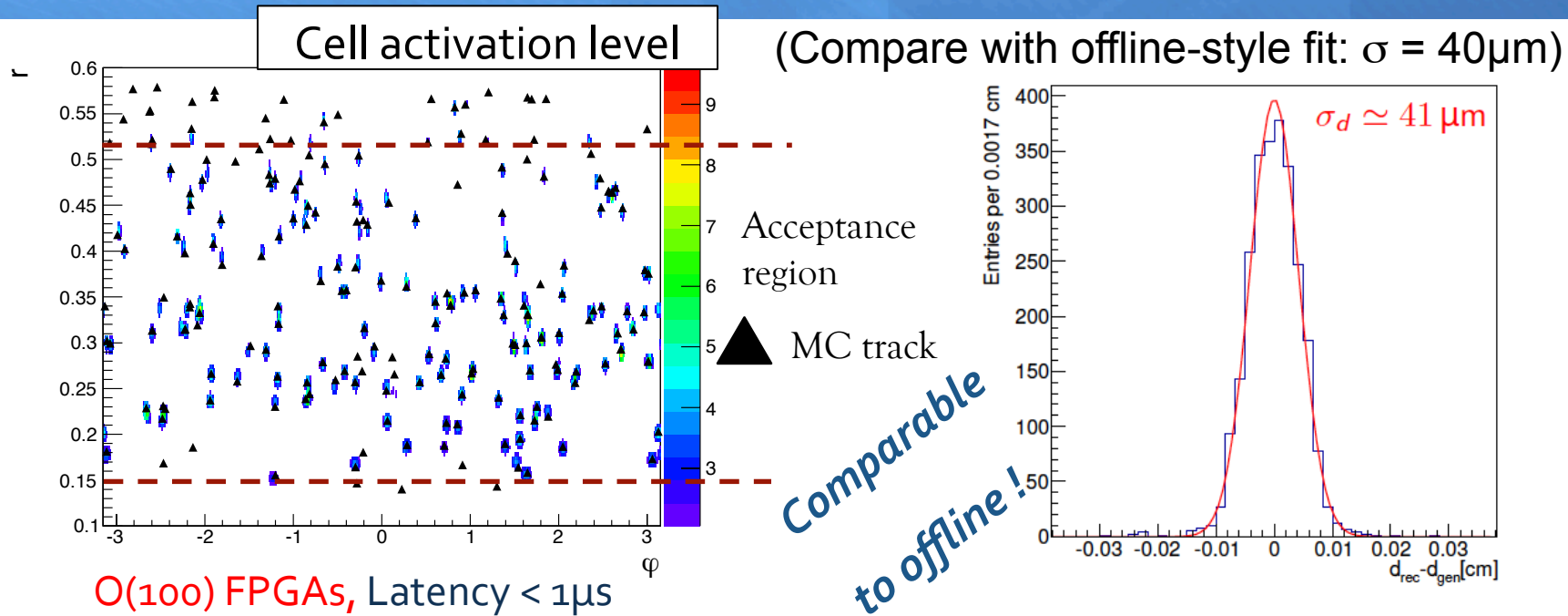


Altera's 28-nm Stratix® V FPGAs deliver the industry's highest of system integration, and ultimate flexibility with reduced core power for high-end applications.

Further progress: R&D for LHCb phase-I

full-MC at phase-I upgrade luminosity

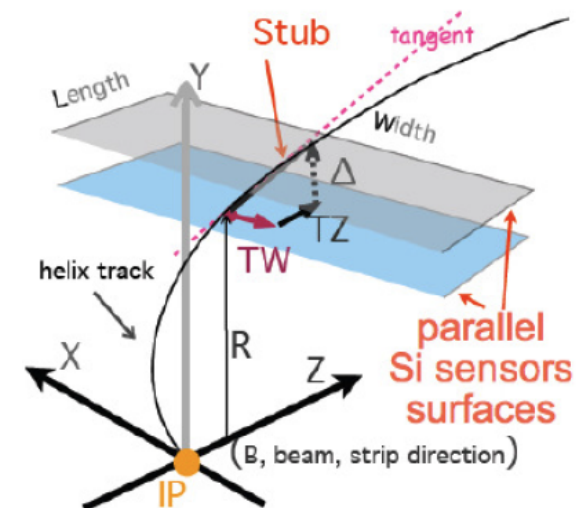
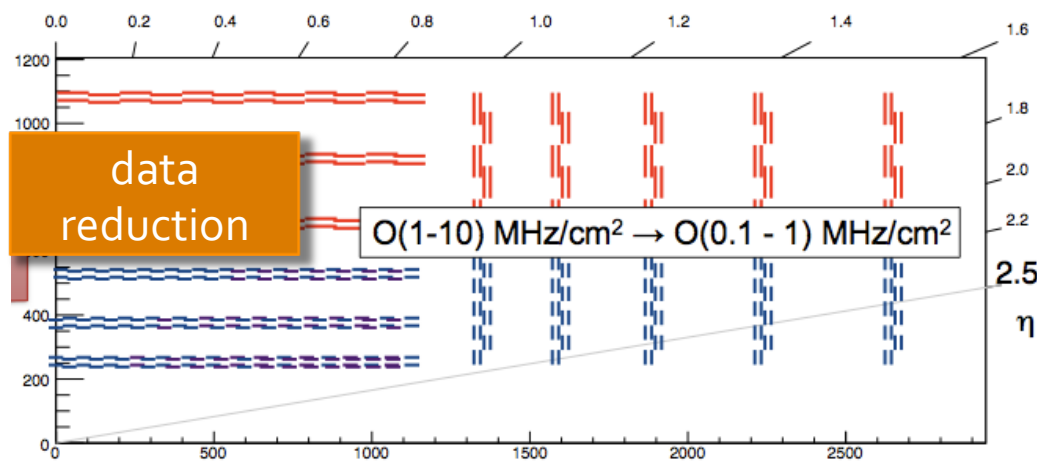
G. Punzi @ INSTR14: <http://cern.ch/go/C6Q5>



- + R&D on paper ~ completed
- + Demonstrator in 2014
- + Supported by INFN and SNS
- + Input for future track triggers

CMS approach

- + detector and readout discussed by F. Palla yesterday
- + Selfseed trigger at 40MHz (strip & pixel-strip)
 - + Readout data rate with $p_T > 2\text{GeV}$ filtering (data reduction $\sim 1/10$)
 - + Hard to solve tracking at 40MHz with single processor
 - + Need time multiplexing over multiple processors
- + (option if L1 latency at $20\mu\text{s}$) pixel trigger seeded by the above

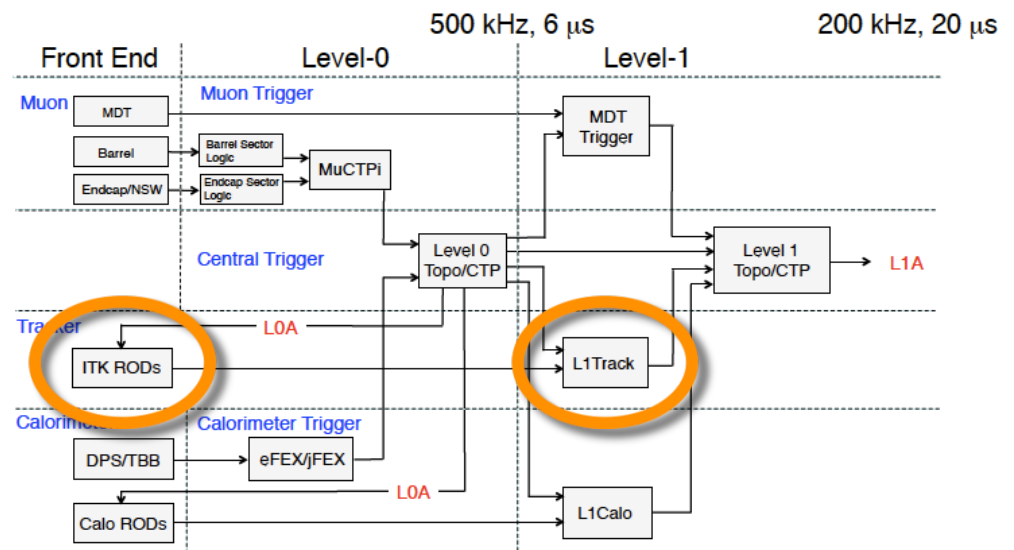
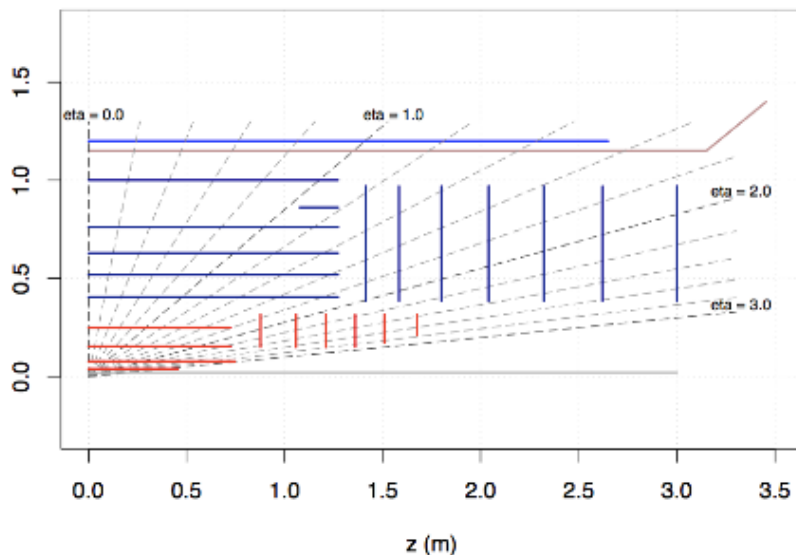


CMS challenges & solutions

- + Data transfer at 40MHz → doable with pT filtering
- + Pattern recognition
 - + pT>2GeV filtering → lower detector occupancy (but 40MHz rate)
 - + Main option based on AM (alternative full FPGA)
 - + Grants low latency (benefit of faster AMchip clock)
 - + **Estimate: a few thousands future (LS3) AM chips**
 - + Considering a goal of 0.5-1M patterns / AMchip
- + Track Fitting FPGA based several algorithms considered
 - + Principal component, retina, Hough transform, tracklets
- + **L1 Track latency ~5μs (+ readout)**
 - + Total L1 latency 10μs (20μs?)

ATLAS approach

- + detector and readout discussed by F. Palla yesterday
- + Approach
 - + Lo rate 500kHz (1MHz)
 - + Regional readout request (R₃) ~ 10% detector
 - + Minimum pT ~5 GeV
 - + Full pixel + strip tracking



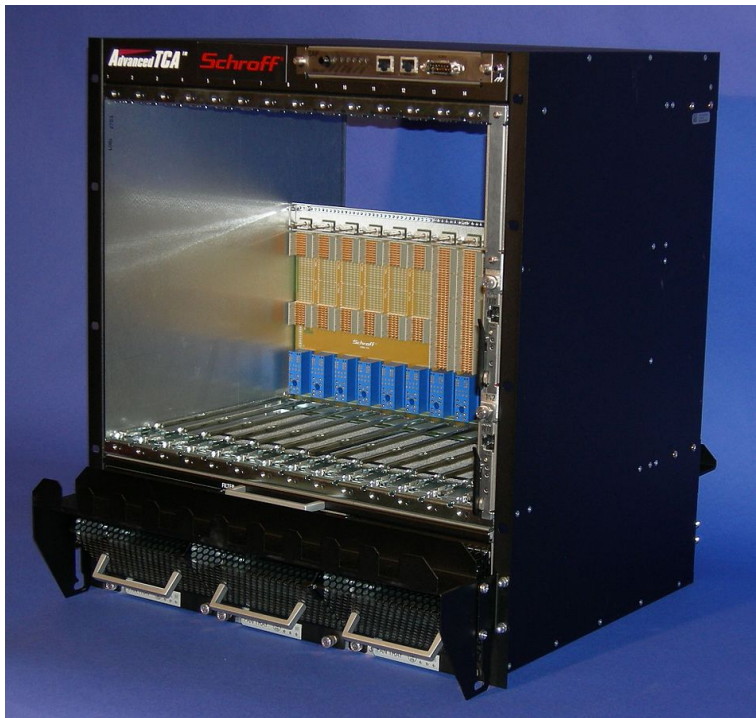
ATLAS challenges & solutions

- + Data transfer
 - + Bandwidth $\sim 10\% * 1\text{MHz} \sim$ equivalent 100kHz full detector
 - + But need to keep latency low $< 6 \mu\text{s}$
- + Pattern recognition
 - + within regions of interest ...
 - + but very complicated: full 140 (max 200) pileup occupancy!!!
 - + Main option based on AM
 - + Grants low latency (benefit of faster AMchip clock)
 - + (gues)stimate O(few thousands) future (LS3) AM chips (goal $\sim 1\text{M}$ patterns / chip)
 - + Simulations starting now
- + Track Fitting FPGA based
- + L1 Track latency $6\mu\text{s}$ (+ readout)

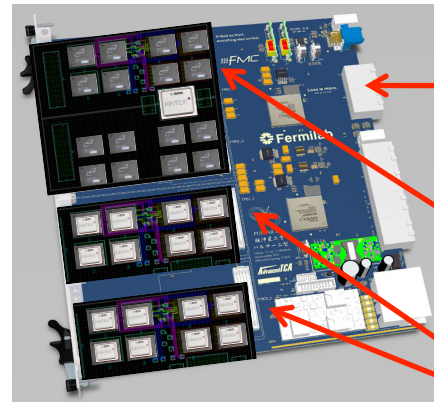
FTK miniaturization & speedup:

(1) ATCA power, (2) New Amchip (40 nm), (3) Multipackaging

(1) ATCA demonstrator



Up to 40Gbps board to board



FTK Data Formatter

2015-2016:
2 AM + FPGA mezzanine

2017-2018:
4 AMSIP mezzanines

- Exploit inter-board ATCA bandwidth and flexibility
- Allow to demonstrate full system potentiality
- Prepare a modular system architecture

(2) New AMchip 40 nm (or 65nm)

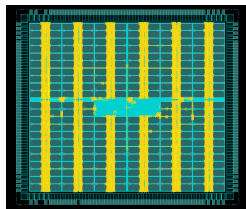
Prepare NEW AM technology core of FTK Phase II and L1Track

Goals: increase pattern density, low power, low latency, other applications

Mini ASIC & MPW 40nm (or 65nm) prototypes

AMchip06 FTK

Design ends in 2014



Full custom AM cell

R&D limited by FTK schedule



Miniasic 40nm
~3mm²
Cheap AM cell
R&D
2015-16



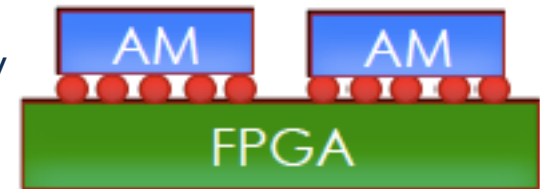
MPW 40nm
~12mm²
usable for ATCA
demonstrator
& system in
package
2016-17

New AMchip 40 nm (200+ MHz?, new functionalities for L1)

AMchip04 AMcell could work O(0.5GHz), but not a goal for FTK.

(3) FTK could become smaller and smaller Multi-packaging FPGA & AMchip – *mini FTK*

- (1) We have a very interesting **quote** for **FPGA bare dies** to be packaged with AMchips
- (2) **IMEC** support for feasibility studies
- (3) **FTK AMSIP** (AM System In Package) becomes a real possibility
Dramatically increases AM to Track Fitter bandwidth
Full 3D technology not required!
- (4) Full 3D explored by Fermilab



R&D coordinated with Fermilab

- System-in-Package integration
 - Die-to-die stacking design
 - Optimize the packaging
 - Thermal power dissipation analysis
- Define a new trigger architecture
 - exploit higher AM-FPGA connectivity

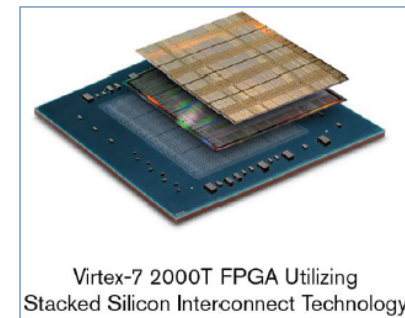
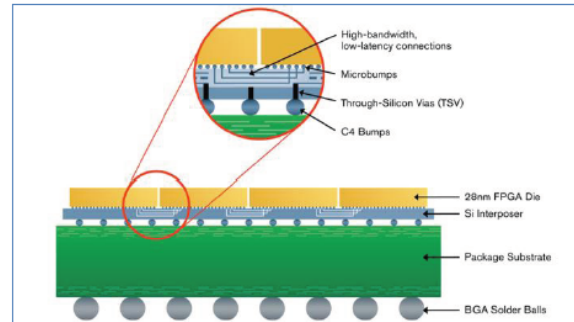
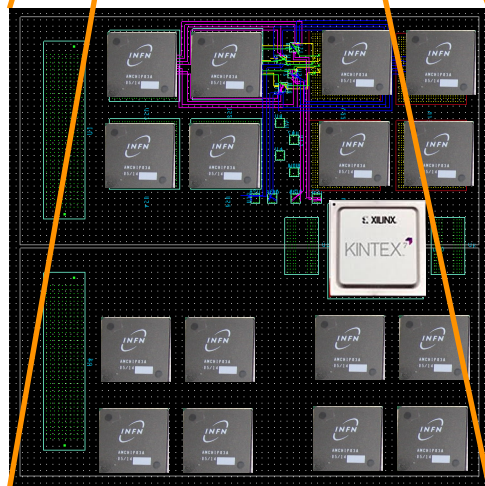
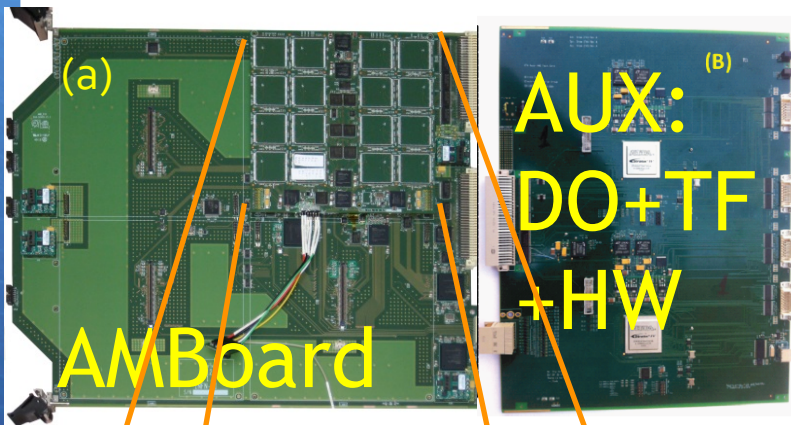


Fig. 1.1.7 Left and right - example of silicon interposer approach for Xilinx Virtex-7 FPGA; This approach will constitute the basis for the innovations that the NEURONS project will develop as described in the text.

1 AM chip
1 FPGA in the
same package

(1-2-3) Compressing AM/FTK size

FTK: AM + Track Fitting (TF)

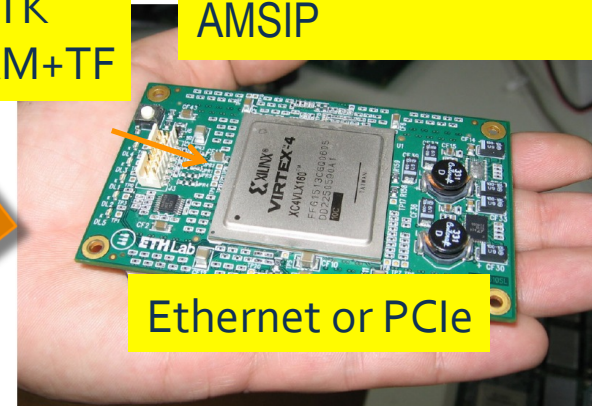


Combine AM & TF
on a mezzanine
~ 1/8 smaller

Goal: build a Lamb that can fit in a PC or can be accessed by a PC.

FTK
AM+TF

What about this size ?
AMSIP



Ethernet or PCIe

Both miniaturization steps:

- Reduce size
- Increase internal bandwidth
- ATCA compatible (ext bandwidth)

Possibility of interdisciplinary applications
with a Ethernet or PCIe connector

R&D plan (being proposed to INFN)

- + The 3 R&D activities shown are of interest to INFN for ATLAS and CMS
 - + CMS needs to start the ATCA demonstrator early 2015
- + Time line 2014-2018
 - + 2014 studies and start on ATCA demonstrator
 - + 2015 studies, ATCA demo, start AM chip (miniasic) design
 - + 2016 AM miniasic submission & test, start AM chip (MPW) design
 - + 2017 test AM chip MPW, design & submission AM System in Package
 - + 2018 test System in Package: standalone, onboard, on ATCA
- + Goals & deliverables: demonstrate Phase-II compatible system
 - + Interconnection bandwidth with ATCA
 - + AM chip: patterns/mm², μ W/pattern/MHz, bandwidth, latency
 - + AM to Track Fitter I/O (System in Package)

Collaborazioni e progetti associati

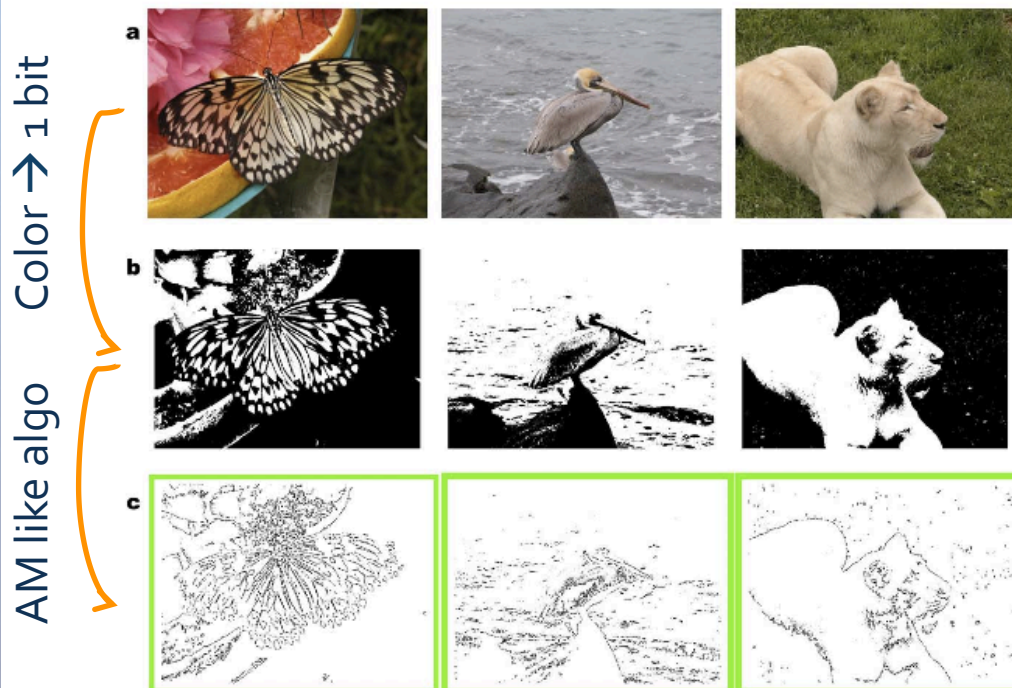
- + Collaborazioni in corso
 - + AMchip: LPNHE, IMEC, Fermilab
 - + AMSIP: LPNHE, IMEC
 - + ATCA: Fermilab, Lione, Northwestern e Karlsruhe
 - + Simulazione HW e fisica: INFN, LPNHE, Lione, Fermilab, Northwestern, Karlsruhe, UCLondon, Uppsala

- + Progetti associati
 - + FP7-PEOPLE-2012-IAPP: Fast Tracker for Hadron Collider Experiments (P. Giannetti)
 - + PRIN: H-TEAM: Trigger, Elettronica Avanzata e Metodi innovativi per misure di precisione nel settore dell' Higgs ad LHC (G. Tonelli)
 - + ANR: Development of a fast processing electronics for track triggering at Hadron Collider Experiments (LPNHE, IPNL Lione)
 - + FP7-PEOPLE-ITN INFIERI (CMS)

- + Next proposals
 - + SIR, ERC, Pillar II (ICT-4), CSN5

Applicazioni interdisciplinari

- + AM chip: a general processor for “data correlation searches”
- + Image reconstruction in various field: e.g. smart cameras
- + Example: imaging



AM like algorithm used to identify salient features of the images.

M. M. Del Viva, G. Punzi, D. Benedetti
DOI: [10.1371/journal.pone.0069154](https://doi.org/10.1371/journal.pone.0069154)

Main focus of the article: which are the most meaningful patterns.

Conclusions

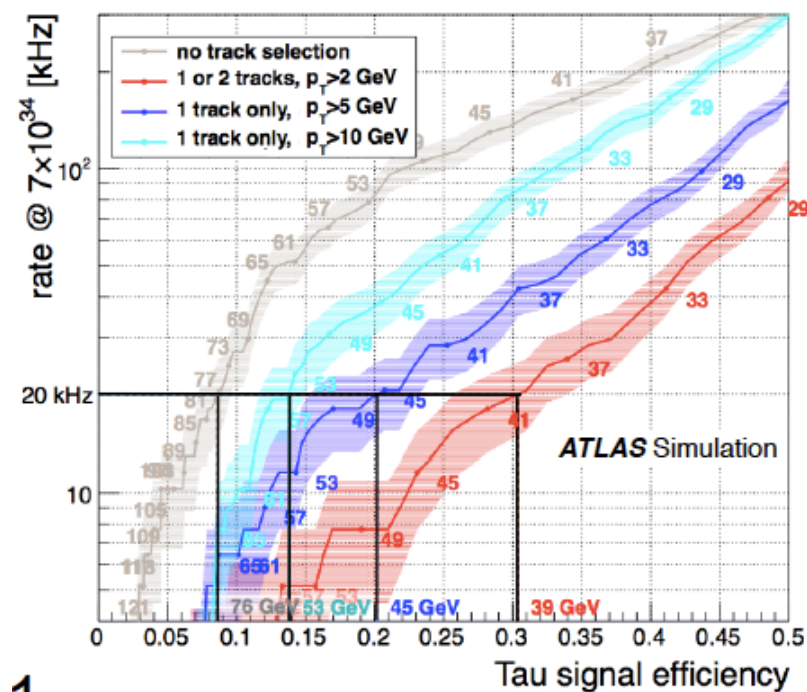
- + To produce a modern-powerful system for
 - Level 1 @ ATLAS & CMS
 - Level 2 @ ATLAS & (L2 Pixel CMS?)
 - Interesting non HEP applications

BACKUP

L1 Track

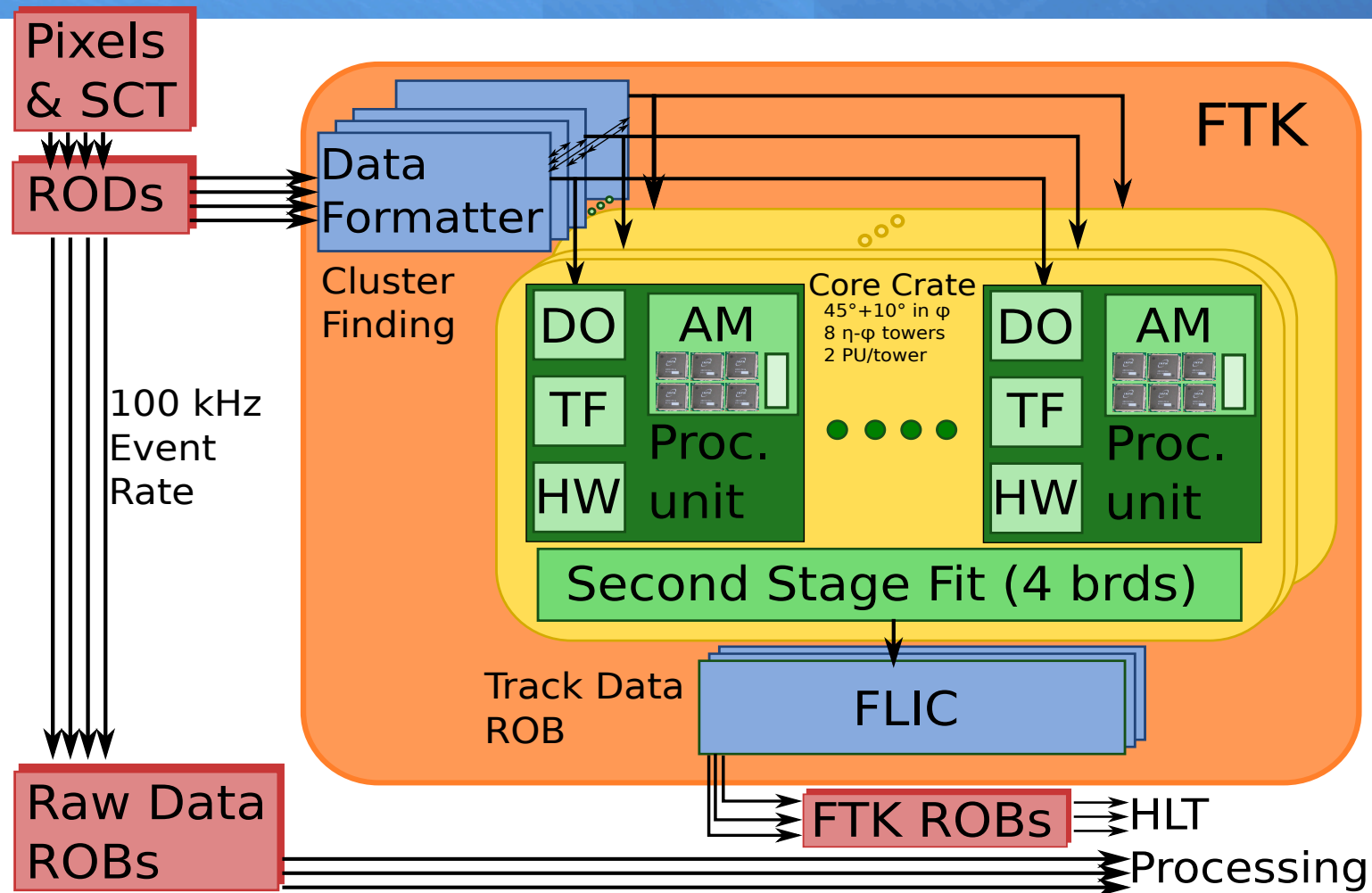
- **Potential benefits** have been studied for **electrons, muons, taus and jets**, single and multiple/combined object triggers using both smeared offline tracks, and smeared truth particles
- Even modest resolution tracking information (p_T , η , ϕ) can provide sufficient rejection
- Rejection factors of between 3 - 10 for muons and electrons respectively, with only small efficiency losses

Example 3x yield for taus signals



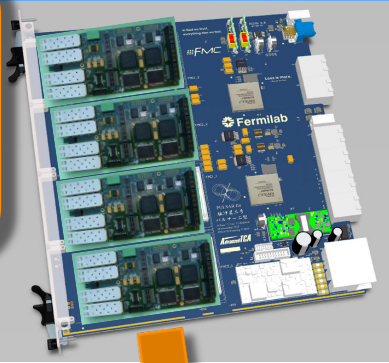
M Sutton - Tracking for the ATLAS Level 1 Trigger for the HL-LHC
ICATPP, 24th September 2013 - Como

FTK in the TDAQ system

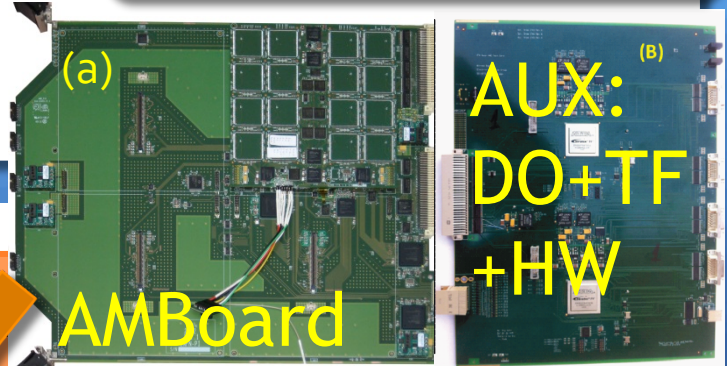


4 FTK_IM/DF do cluster finding. ATCA DF distributes clusters to 64 FTK η - ϕ towers.

128 PUs do pattern matching and the 1st stage track fitting.



System



Pixels & SCT
RODs

Data Formatter

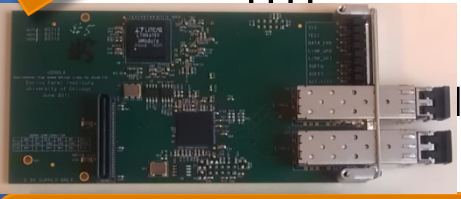
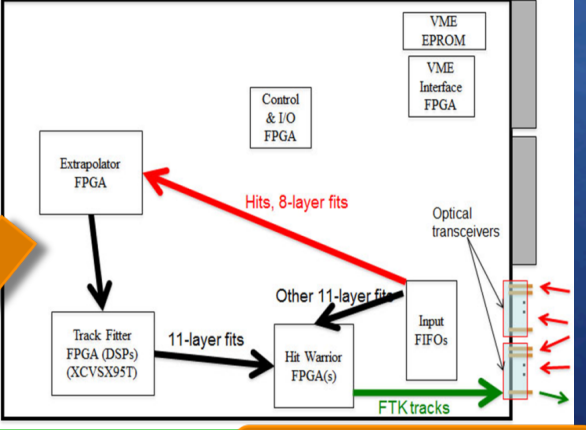
Cluster Finding

DO AM
TF Proc. unit
HW

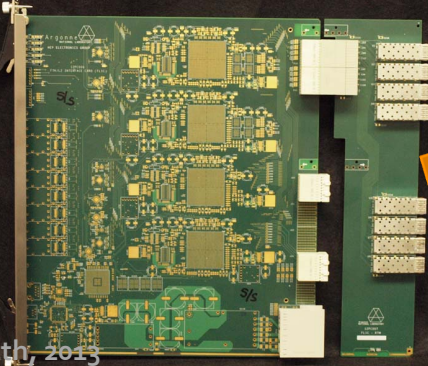
Core Crate
45°+10° in ϕ
8 η - ϕ towers
2 PU/tower

Second Stage Fit (4 brds)

Do full 12 layer fit



Sends SCT & pixel data to DAQ & FTK.



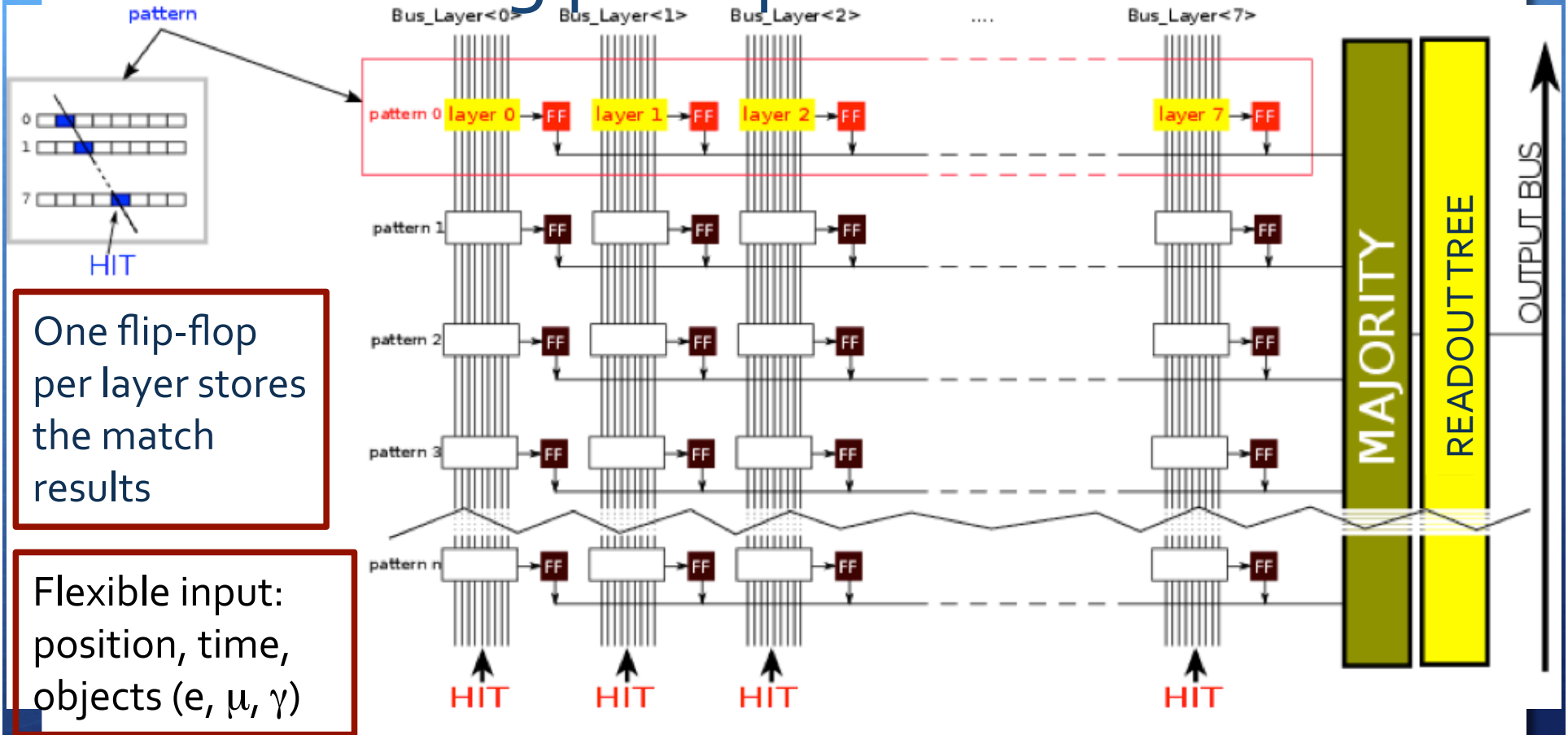
FLIC sends tracks to ROS's. ATCA for global function TBD

FLIC

FTK ROBs

HLT
Processing

AM working principle



One flip-flop per layer stores the match results

Flexible input: position, time, objects (e , μ , γ)

Pattern matching is completed as soon as all hits are loaded.
 Data arriving at different times is compared in parallel with all patterns.
 Unique to AM chip: look for correlation of data received at different times.

AM chip scaling

Semiconductor manufacturing processes

10 μm – 1971
3 μm – 1975
1.5 μm – 1982
1 μm – 1985
800 nm – 1989
600 nm – 1994
350 nm – 1995
250 nm – 1997
180 nm – 1999
130 nm – 2002
90 nm – 2004
65 nm – 2006
45 nm – 2008
32 nm – 2010
22 nm – 2012
14 nm – 2014
10 nm – est. 2015
7 nm – est. 2017
5 nm – est. 2019

Half-nodes

V•T

- + Scale effects
 - + O(1000) medium size FPGAs are more expensive than AMchips
- + The AM chip is a memory
 - + There is a large degree of programmability

180nm in 2005 (5k patterns, 46kbits) AMchip03 (CDF)

65nm in 2014 (128k patterns, 18Mbits) AMchip06 (FTK planned)

Scaled up by factor ~40 in 9 years!

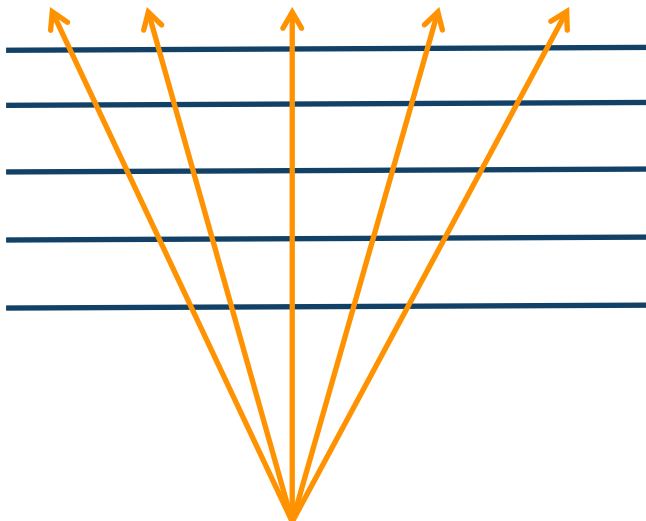
Lot of design R&D beyond process size reduction!

There is always a pattern

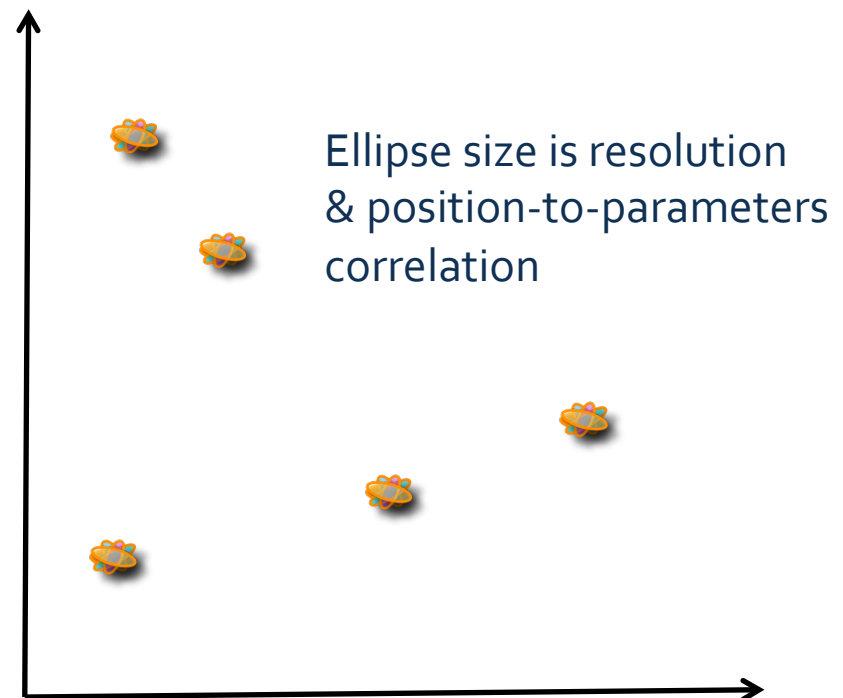
- + Associative Memory (and similar algorithms)
 - + define a pattern in the hit (measurement) space
 - + a pattern is a dedicated piece of electronics
 - + patterns are discrete
- + Hough transform, other
 - + define a “pattern” in the “track parameter” space
 - + usually a “pattern” has its own logic
 - + patterns can be discrete or contiguous

Easy most tracking

- + Point like source
- + Strait tracks only
 - + 2 parameters
 - + 1 hit (pix or stereo-strips) determines the track

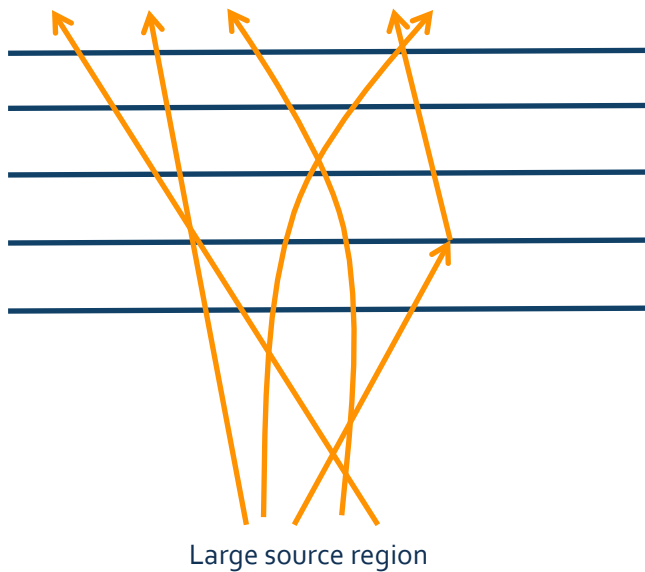


Track phase space

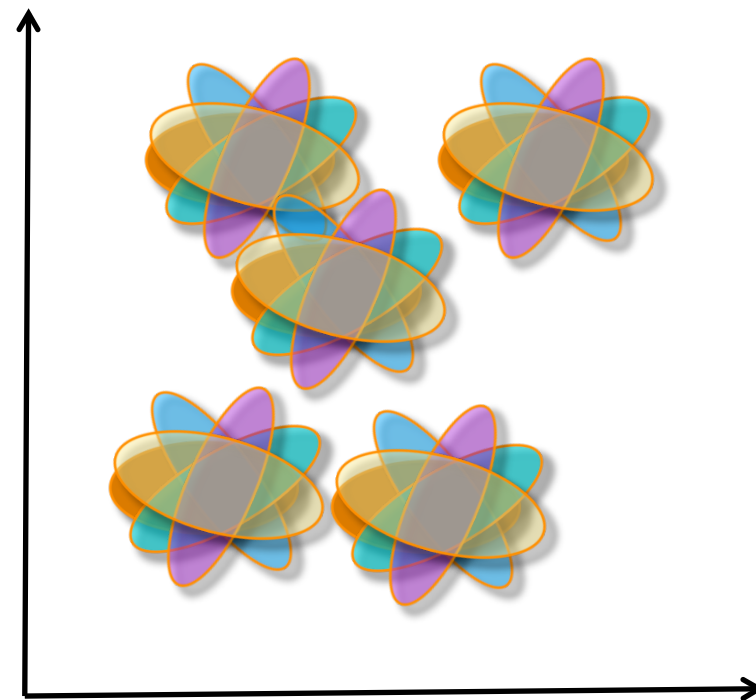


Adding more track parameters

- + Adding curvature and significant multiple scattering
- + Large source size (w.r.t. effect of curvature & M.S.)
- + Tracking becomes highly non local

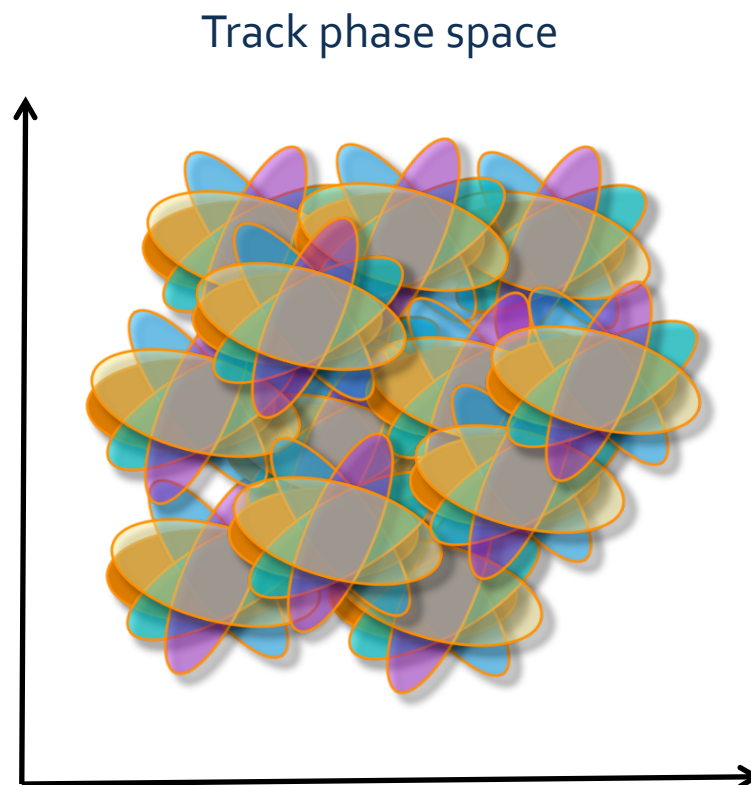
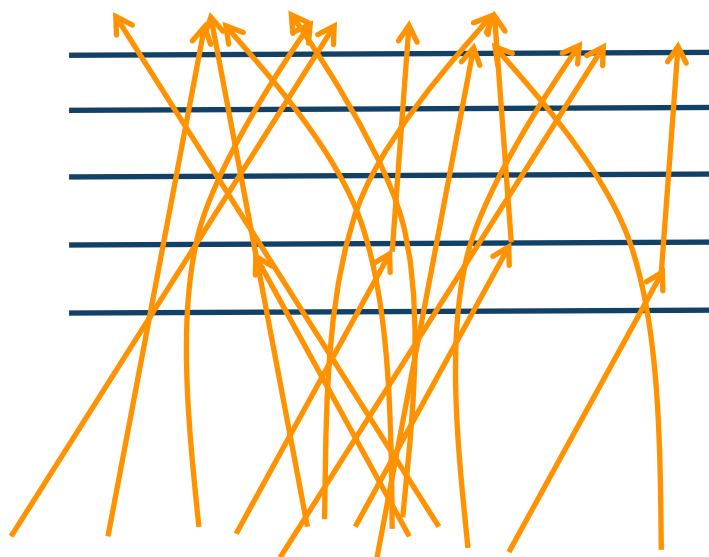


Track phase space



Increasing occupancy

- + When occupancy high w.r.t. "hit size in track phase space"
- + → tracking is tough



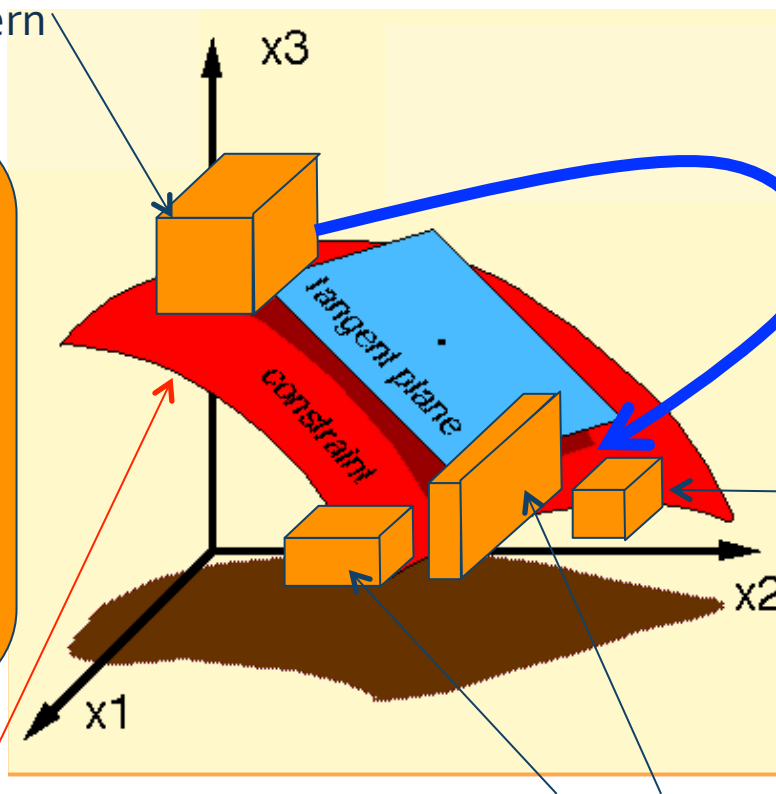
Variable resolution Associative Memory combines advantages of both hit space, and trk parameter space

The patterns: a different point of view

Large pattern

5 strip + 3 pixel layers
→ 11 coordinates
→ 11D hit coord. space

The pattern bank:
• covers the track manifold with patterns.
• covered space outside manifold → acceptance for fakes
• with variable resolution → dramatically improves S/N



For example: a factor of 2 better resolution on each coordinate
→ a factor 2^{11} less matching volume

Thin pattern

Fixed resolution patterns → fixed aspect ratio

5D track manifold

Variable resolution patterns